





Technical Data Sheet (Vers. V01)

S-Bond[®]er Ultrasonic-Soldering Machines 57/150 and 40/200

Mobile Soldering and metallization. Lead free, no fluxes, processing at air. Soldering manifold materials by using SBond[®] solder materials

In according to RoHS (2002/95/EG) and WEEE

Technical Datas	Device - ID	
	57/150	40/200
		
Ultrasonic frequency	57 kHz +/- 3 kHz – resonance frequency automatically successive	40 kHz +/- 3 kHz – resonance frequency automatically successive
Main output	12 W max.	15 W max.
Temperature range	150 °C – 500 °C continuously variable	150 °C – 500 °C continuously variable
Heat output	heat coil 125 W	heat coil 175 W
Power supply	115 V, 230 V AC 50/ 60 Hz	115 V, 230 V AC 50/ 60 Hz
Weight – tabletop unit	Ca. 3,5 kg	Ca. 3,5 kg
Weight – hand soldering unit	~ 0,3 kg	~ 0,3 kg
External dimension	210 (W) x 135 (H) x 270 (D) mm	250 (W) x 120 (H) x 270 (D) mm
Material of the soldering tip	special stainless steel	special stainless steel
Soldering tips	Ø 1 mm to Ø 5 mm,	Ø 6 mm to Ø 12 mm, up to 22 mm on request
Soldering tips can be coated optionally	on request	on request
Dimension up to which the tip can be abraded	within 10 mm	within 10 mm
Material of the hand grip	plastics (ABS)	plastics (ABS)

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